



FINAL PRODUCT/PROCESS CHANGE NOTIFICATION

Generic Copy

13-Mar-2007

SUBJECT: ON Semiconductor Final Product/Process Change Notification # 15747

TITLE: Qualification of OSPI for Assembly/Test of 8/14/16/20/24/28 Lead SOIC Wide and Narrow Body Packages

PROPOSED FIRST SHIP DATE: 13-May-2007

**AFFECTED CHANGE CATEGORY(S): ON SEMICONDUCTOR ASSY SITE
ON SEMICONDUCTOR TEST SITE**

**AFFECTED PRODUCT DIVISION(S): MOS POWER PRODUCTS
ANALOG PRODUCTS
DISCRETE PRODUCTS
LOGIC PRODUCTS**

FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:

Contact your local ON Semiconductor Sales Office or Alan Garlington<alan.garlington@onsemi.com>

SAMPLES: Contact your local ON Semiconductor Sales Office

ADDITIONAL RELIABILITY DATA: Available

Contact your local ON Semiconductor Sales Office or Matt Kas<Matt.Kas@onsemi.com>

NOTIFICATION TYPE:

Final Product/Process Change Notification (FPCN)

Final change notification sent to customers. FPCNs are issued at least 60 days prior to implementation of the change.

ON Semiconductor will consider this change approved unless specific conditions of acceptance are provided in writing within 30 days of receipt of this notice. To do so, contact your local ON Semiconductor Sales Office.

DESCRIPTION AND PURPOSE:

This is a Final Process Change Notice to IPCN 15621 available at www.onsemi.com notifying customers of the capacity expansion of the ON Semiconductor assembly/test location at Carmona, Philippines (OSPI) for 8/1416/20/24/28 lead Wide and Narrow body SOIC packages. The devices listed on this FPCN are assembled / tested at the ASE assembly/test facility located in Chung Li, Taiwan. At the expiration of this Final PCN, these devices may be processed at either location.

This is the second Final PCN for this program. Devices will be qualified in phases with only those devices listed below affected by this FPCN.



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RELIABILITY DATA SUMMARY:

Qualification Vehicles:

A = 20 Lead Wide = MC74VHC245DW	0.80 x 1.130 mm Die Size	3 Lots
B = 16 Lead Wide = CS5101EDWR16	3.560 x 4.080 mm Die Size	3 Lots
C = 16 Lead Wide = MC33363A	2.610 x 3.420 mm Die Size	3 Lots

Reliability Test Results:

Test	Conditions	Results		
		Group A	Group B	Group C
Preconditioning	3 pass@ 260C	0/693	0/693	0/693
Precod. Temp Cycle	-65 to +150 C 500 Cyc	0/231	0/231	0/231
Precond. Autoclave	Ta=121C; RH= 96 Hrs 100% ; PSIG=15	0/231	0/231	0/231
HTOL	Ta = 125C 504 Hrs	0/231	0/231	0/231
Scanning Acoustic Tomography	Check for Delamination	0/15	0/15	0/15
Bond Pull	After 500 Temp Cycle 5 Units; 30 Bonds	0/90		
Ball Shear	10 units/lot	0/30		

All groups pass minimum of MSL 3 at 260 C

ELECTRICAL CHARACTERISTIC SUMMARY:

Electrical performance will not change.

CHANGED PART IDENTIFICATION:

All devices processed at the new OSPI location will have the location code "P" as part of the device traceability code.



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AFFECTED DEVICE LIST

- CS41077DWR16
- CS5101EDW16
- CS5101EDW16G
- CS5101EDWR16
- CS5101EDWR16G
- MC33362DW
- MC33362DWG
- MC33362DWR2
- MC33362DWR2G
- MC33362XDWR2
- MC33362XDWR2G
- MC33363ADW
- MC33363ADWG
- MC33363ADWR2
- MC33363ADWR2G
- MC33363BDW
- MC33363BDWG
- MC33363BDWR2
- MC33363BDWR2G
- MC33363DW
- MC33363DWR2
- MC74LCX240DWR2
- MC74LCX240DWR2G
- MC74LCX244DW
- MC74LCX244DWG
- MC74LCX244DWR2
- MC74LCX244DWR2G
- MC74LCX245DW
- MC74LCX245DWG
- MC74LCX245DWR2
- MC74LCX245DWR2G
- MC74LCX373DWR2
- MC74LCX373DWR2G
- MC74LCX374DW
- MC74LCX374DWR2
- MC74LCX374DWR2G
- MC74LCX540DWR2
- MC74LCX540DWR2G
- MC74LCX541DW
- MC74LCX541DWG
- MC74LCX541DWR2
- MC74LCX541DWR2G
- MC74LCX573DW
- MC74LCX573DWG
- MC74LCX573DWR2
- MC74LCX573DWR2G
- MC74LCX574DW
- MC74LCX574DWR2
- MC74LCX574DWR2G
- MC74LVX240DWR2
- MC74LVX240DWR2G
- MC74LVX244DW
- MC74LVX244DWR2
- MC74LVX244DWR2G



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- MC74LVX245DW
- MC74LVX245DWR2
- MC74LVX245DWR2G
- MC74LVX373DW
- MC74LVX373DWR2
- MC74LVX373DWR2G
- MC74LVX374DWR2
- MC74LVX374DWR2G
- MC74LVX4245DW
- MC74LVX4245DWG
- MC74LVX4245DWR2
- MC74LVX4245DWR2G
- MC74LVX541DW
- MC74LVX541DWG
- MC74LVX573DWR2
- MC74LVX573DWR2G
- MC74LVX574DWR2
- MC74LVX574DWR2G
- MC74LVXC3245DWR2
- MC74LVXC3245DWRG
- MC74VHC240DWR2
- MC74VHC240DWR2G
- MC74VHC244DW
- MC74VHC244DWR2
- MC74VHC244DWR2G
- MC74VHC245DW
- MC74VHC245DWG
- MC74VHC245DWR2
- MC74VHC245DWR2G
- MC74VHC373DWR2
- MC74VHC373DWR2G
- MC74VHC374DWR2
- MC74VHC374DWR2G
- MC74VHC540DW
- MC74VHC540DWR2
- MC74VHC540DWR2G
- MC74VHC541DWR2
- MC74VHC541DWR2G
- MC74VHC573DW
- MC74VHC573DWR2
- MC74VHC573DWR2G
- MC74VHC574DW
- MC74VHC574DWG
- MC74VHC574DWR2
- MC74VHC574DWR2G
- MC74VHCT240ADWR2
- MC74VHCT240ADWRG
- MC74VHCT244ADW
- MC74VHCT244ADWR2
- MC74VHCT244ADWRG
- MC74VHCT245ADW
- MC74VHCT245ADWG
- MC74VHCT245ADWR2
- MC74VHCT245ADWRG
- MC74VHCT373ADWR2
- MC74VHCT373ADWRG



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MC74VHCT374ADWR2
MC74VHCT374ADWRG
MC74VHCT541ADW
MC74VHCT541ADWG
MC74VHCT541ADWR2
MC74VHCT541ADWRG
MC74VHCT573ADW
MC74VHCT573ADWG
MC74VHCT573ADWR2
MC74VHCT573ADWRG
MC74VHCT574ADW
MC74VHCT574ADWG
MC74VHCT574ADWR2
MC74VHCT574ADWRG
SCY99041DWR2
MC74HCT244ADWR2G
CS92404BDW16
CS92404BDWR16
CS92404BDWR16G
SC79176BDR2
SC79176DR2
SC79176DNLR2
SC74808DR2
SC79155DR2
SCY994403DR2
MC33151VD
SC79140DR2
SC79156DR2
SC79181DR2
SC79183DR2
TY40459DR2
TY40460R2
TY40470R2
TYA33164D-5R2
SCY99011DR2